Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**B**

**E**

**.019”**

**.019”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004” X .004”**

**Backside Potential: COLLECTOR**

**Mask Ref: 117**

**APPROVED BY: DK DIE SIZE .019” X .019” DATE: 9/7/21**

**MFG: MOTOROLA THICKNESS .008” P/N: 2N2222A**

**DG 10.1.2**

#### Rev B, 7/19/02